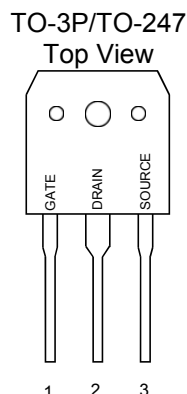
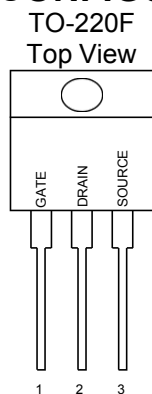




GENERAL DESCRIPTION

This high voltage MOSFET uses an advanced termination scheme to provide enhanced voltage-blocking capability without degrading performance over time. In addition, this advanced MOSFET is designed to withstand high energy in avalanche and commutation modes. The new energy efficient design also offers a drain-to-source diode with a fast recovery time. Designed for high voltage, high speed switching applications in power supplies, converters and PWM motor controls, these devices are particularly well suited for bridge circuits where diode speed and commutating safe operating areas are critical and offer additional and safety margin against unexpected voltage transients.

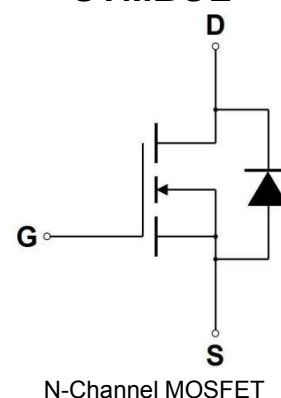
PIN CONFIGURATION



FEATURES

- ◆ Robust High Voltage Termination
- ◆ Avalanche Energy Specified
- ◆ Source-to-Drain Diode Recovery Time Comparable to a Discrete Fast Recovery Diode
- ◆ Diode is Characterized for Use in Bridge Circuits
- ◆ I_{DSS} and $V_{DS(on)}$ Specified at Elevated Temperature
- ◆ Isolated Mounting Hole Reduces Mounting Hardware

SYMBOL



ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain to Current — Continuous	$I_{D(1)}$	34.6	A
— Pulsed	I_{DM}	104	A
Gate-to-Source Voltage — Continue	V_{GS}	± 20	V
Total Power Dissipation — TO-220FP	P_D	42	W
—TO-3P		329	
—TO-247		298	
Derate above 25°C — TO-220FP		0.33	W/°C
—TO-3P		2.63	
—TO-247		2.38	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C
Single Pulse Drain-to-Source Avalanche Energy — $T_J = 25^\circ\text{C}$ ($V_{DD} = 100\text{V}$, $V_{GS} = 10\text{V}$, $I_L = 10\text{A}$, $L = 10\text{mH}$, $R_G = 25\Omega$)	E_{AS}	1498	mJ
Thermal Resistance — Junction to Case -TO-220FP	θ_{JC}	3	°C/W
— Junction to Case -TO-3P		0.38	
— Junction to Case -TO-247		0.42	
— Junction to Ambient -TO-220FP		62.5	
— Junction to Ambient -TO-3P, TO-247		40	
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	T_L	260	°C

(1) Drain current limited by maximum junction temperature



GWM35S65

POWER FIELD EFFECT TRANSISTOR

ORDERING INFORMATION

Part Number	TOP MARK	Part Number	Packing Mthod	Note
GWM35S65XN220FP(Note1)	GWM35S65X	TO-220FP	Tube	
GWM35S65XN3P(Note1)	GWM35S65X	TO-3P	Tube	
GWM35S65XN247(Note1)	GWM35S65X	TO-247	Tube	

Note1: X : Suffix for Halogen Free Product,

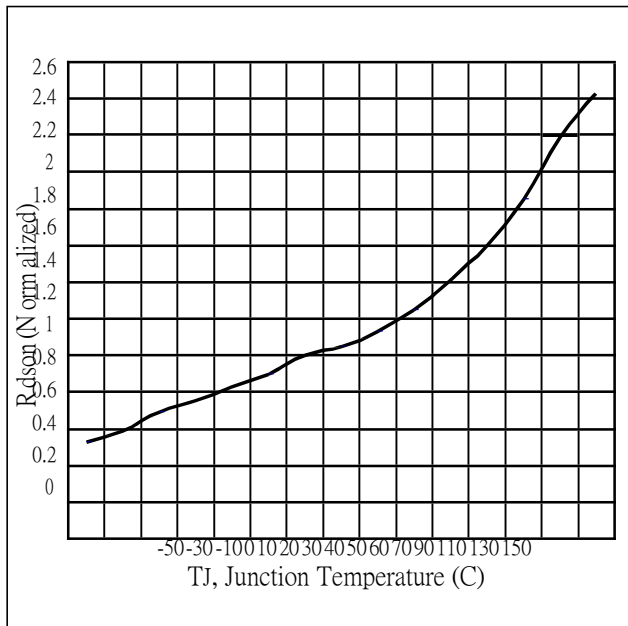
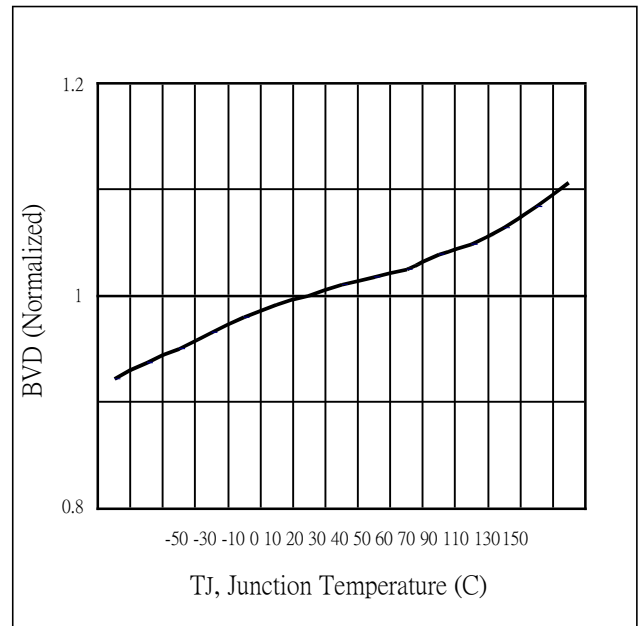
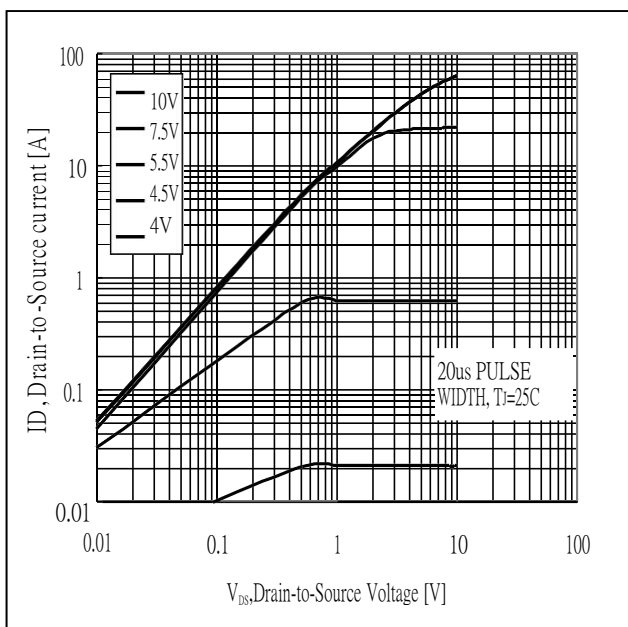
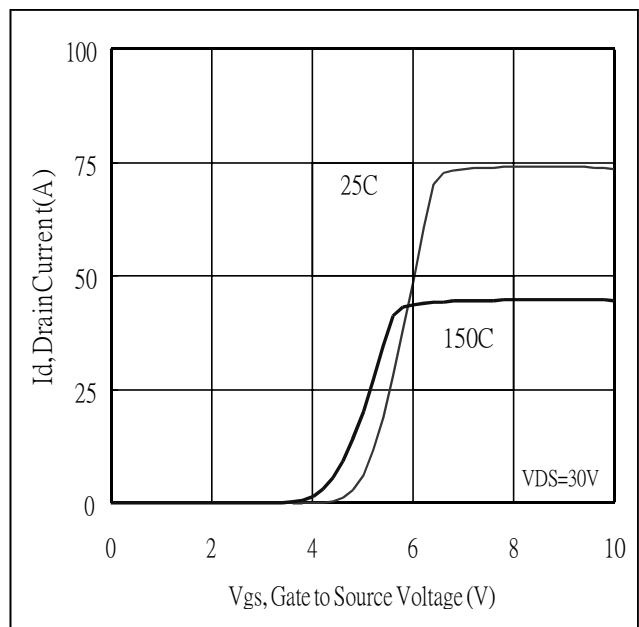
ELECTRICAL CHARACTERISTICS

Unless otherwise specified, $T_J = 25^{\circ}\text{C}$.

		GWM35S65				
Characteristic		Symbol	Min	Typ	Max	Units
Drain-Source Breakdown Voltage (V _{GS} = 0 V, I _D = 250 μA)		V _{(BR)DSS}	650			V
Drain-Source Leakage Current (V _{DS} =650 V, V _{GS} = 0 V)		I _{DSS}			1	uA
Gate-Source Leakage Current-Forward (V _{gsf} = 20 V, V _{DS} = 0 V)		I _{GSSF}			100	nA
Gate-Source Leakage Current-Reverse (V _{gsr} = - 20 V, V _{DS} = 0 V)		I _{GSSR}			100	nA
Gate Threshold Voltage (V _{DS} = V _{GS} , I _D = 250 μA)		V _{GS(th)}	2	3	4	V
Static Drain-Source On-Resistance (V _{GS} = 10 V, I _D = 11.7A) *		R _{DS(on)}			110	mΩ
Gate resistance (f=1MHz, open drain)		R _G		3.7		Ω
Input Capacitance	(V _{DS} =100 V, V _{GS} = 0 V, f = 1.0 MHz)	C _{iss}		3269		pF
Output Capacitance		C _{oss}		105		pF
Reverse Transfer Capacitance		C _{rss}		39		pF
Turn-On Delay Time	(V _{DD} = 325 V, I _D = 35 A, R _G = 25Ω) *	t _{d(on)}		39.7		ns
Rise Time		t _r		113.8		ns
Turn-Off Delay Time		t _{d(off)}		97.9		ns
Fall Time		t _f		57.8		ns
Total Gate Charge	(V _{DS} = 520 V, I _D = 35 A, V _{GS} = 10 V)*	Q _g		51.1		nC
Gate-Source Charge		Q _{gs}		18.2		nC
Gate-Drain Charge		Q _{gd}		21.3		nC
SOURCE-DRAIN DIODE CHARACTERISTICS						
Forward On-Voltage(1)	(I _S = 35 A, d _{IS} /d _t = 100A/μs)	V _{SD}			1.5	V
Forward Turn-On Time		t _{on}		**		ns
Reverse Recovery Time		t _{rr}		528.66		ns

* Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$

** Negligible, Dominated by circuit inductance

**TYPICAL ELECTRICAL CHARACTERISTICS****Fig 1. On-Resistance Variation with vs. Temperature****Fig.2 Breakdown Voltage Variation vs. Temperature****Fig 3. Typical Output Characteristics****Fig 4. Typical Transfer Characteristics**

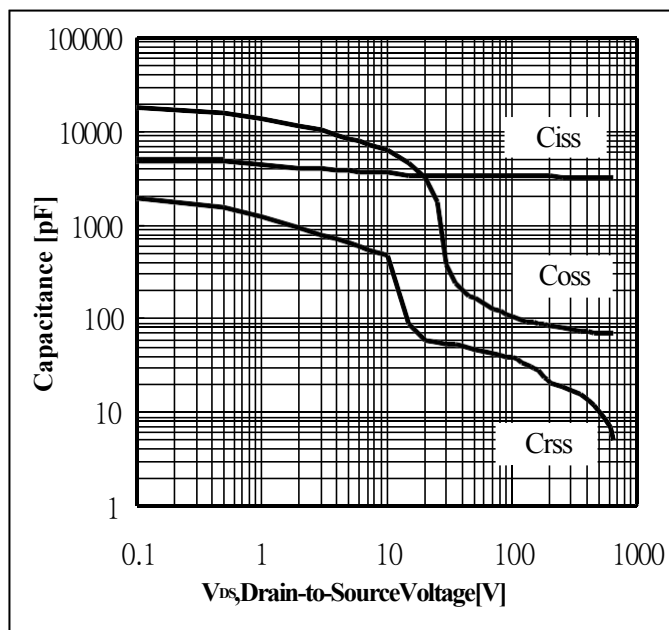


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

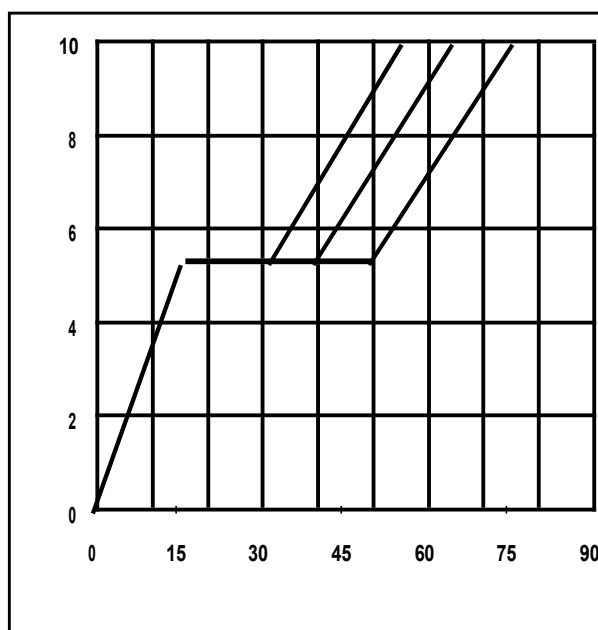


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage